

Current Production Information								
TI Part Number		TLV2782ID		Assembly Site		TI TAIWAN A/T		
Lead/Ball Finish		CU NIPDAU		Package Type / Pins		D 8		
Planned Lead/Ball Finish				Package Body Size (WxLxH) mm		3.91x4.9x1.58		
MSL / Reflow Ratings		Level-1-260C-UNLIM		Total Device Mass (mg)		75.863091		
Environmental Ratings Information								
Part Number Type		Std		JIG Material Content Compliance		Level A & B		
RoHS & High-Temp Compliant		Y		Green Compliant		Y		
Pb-Free (RoHS) Conversion Date		15-Feb-2004 (DC 0408)		Green Conversion Date		01-Feb-2005 (DC 0506)		
Pb-Free (RoHS) Available Supply Date		24-Nov-2004		Green Available Supply Date		31-Jul-2006		
Component Information								
Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level		
				Percentage %	ppm	Percentage %	ppm	
Bond Wire								
Metallurgy	Gold	7440-57-5	0.09999	99.993	999929	0.1318	1318	
Trace Metal	Beryllium	7440-41-7	0.000001	0.001	10	0	0	
Trace Metal	Calcium	7440-70-2	0.000001	0.001	10	0	0	
Trace Metal	Indium	7440-74-6	0.000003	0.003	30	0	0	
Trace Metal	Silver	7440-22-4	0.000002	0.002	20	0	0	
Sub-Total			0.099997	100	1000000	0.1318	1318	
Die Attach Adhesive								
Conductive Material	Silver	7440-22-4	0.56	70	700000	0.7382	7381	
Polymer	Epoxy		0.104	13	129999	0.1371	1370	
Polymer	Proprietary Resin		0.044	5.5	54999	0.058	579	
Reactive Diluent	Proprietary Material		0.092	11.5	115000	0.1213	1212	
Sub-Total			0.8	100	1000000	1.0545	10542	
Lead Frame								
Base Metal	Copper	7440-50-8	24.416166	97.425	974250	32.1845	321845	
Base Metal	Iron	7439-89-6	0.601476	2.4	24000	0.7928	7928	
Base Metal	Lead	7439-92-1	0.007518	0.03	299	0.0099	99	
Base Metal	Phosphorus	7723-14-0	0.003759	0.015	149	0.005	49	
Base Metal	Tin	7440-31-5	0.007518	0.03	299	0.0099	99	
Base Metal	Zinc	7440-66-6	0.025061	0.1	999	0.033	330	
Sub-Total			25.061498	100	1000000	33.0352	330350	
Lead Frame Plating								
Plating	Gold	7440-57-5	0.0003	0.7792	7792	0.0004	3	
Plating	Nickel	7440-02-0	0.036621	95.122	951219	0.0483	482	
Plating	Palladium	7440-05-3	0.001578	4.0988	40988	0.0021	20	
Sub-Total			0.038499	100	1000000	0.0507	505	
Mold Compound								
Coloring	Carbon Black	1333-86-4	0.141489	0.3	2999	0.1865	1865	
Filler	Fused Silica	60676-86-0	35.843955	76	760000	47.2482	472482	
Flame Retardant Additive	Proprietary Non Halide		1.650708	3.5	34999	2.1759	21759	
Hardener	Phenolic Novolac		3.537232	7.5	74999	4.6627	46626	
Other additives	Catalyst Mold Release Adhesion Agent		1.745035	3.7	37000	2.3002	23002	
Polymer	Cresol Novolac Epoxy		3.537232	7.5	74999	4.6627	46626	
Stress Relief Agent	Proprietary		0.707446	1.5	14999	0.9325	9325	
Sub-Total			47.163097	100	1000000	62.1687	621685	
Semiconductor Device								
Silicon Chip	Doped Silicon	7440-21-3	2.7	100	1000000	3.559	35590	
Sub-Total			2.7	100	1000000	3.559	35590	
Total			75.863091			100	1000000	

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor Products

TI certifies that the material content information provided by TI as of the date of disclosure is representative and accurate. TI semiconductor products designated by TI as "Pb-Free" or "Green" (defined below) do not exceed any of the Joint Industry Guide (JIG) Level-A Substance thresholds and are compliant with the requirements of the European Union's Restriction on Use of Hazardous Substances ("RoHS") Directive, 2002/95/EC.

For TI semiconductor products NOT designated as "Pb-Free" or "Green", these products are RoHS compliant with the exception of Lead (Pb) which may be found in the leadframe plating or solder balls, or in RoHS exempt applications such as high-temperature solder die attach (exemption 7a) and flip-chip solder bumps (exemption 15). This situation is known as RoHS-5 or "5 of 6" compliant.

JIG Level-A Banned Substances	Threshold, Homogeneous Level (1)
Asbestos	Not intentionally added
Azo colorants	Not intentionally added
RoHS - Cadmium/Cadmium Compounds	75 ppm, Not intentionally added (RoHS threshold = 100ppm)
RoHS - Hexavalent Chromium/Hex.Chromium.Compounds	1000 ppm, Not intentionally added
RoHS - Lead/Lead Compounds	1000 ppm, Not intentionally added
RoHS - Mercury/Mercury Compounds	1000 ppm, Not intentionally added
Ozone Depleting Substances	Class I : Not intentionally added Class II : 1000ppm
RoHS - Polybrominated Biphenyls (PBBs)	1000 ppm, Not intentionally added
RoHS - Polybrominated Diphenyl Ethers (PBDEs)	1000 ppm, Not intentionally added
Polychlorinated Biphenyls (PCBs)	1000 ppm, Not intentionally added
Polychlorinated Naphthalenes (>3 Chlorine atoms)	1000 ppm, Not intentionally added
Radioactive Substances	1000 ppm, Not intentionally added
Shortchain Chlorinated Paraffins	1000 ppm, Not intentionally added
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	1000 ppm, Not intentionally added
Tributyl Tin Oxide (TBTO)	1000 ppm, Not intentionally added
(1) Threshold does not apply to applications covered by a RoHS substance exemption.	

Regarding the EU Directive 2004/12/EC concerning Packaging and Packaging Waste, TI's packing materials (boxes, trays, etc) comply with the directive's requirement that the total concentration of the 4 heavy metals (cadmium, hexavalent chromium, lead, and mercury) must not exceed 100 ppm. Material content details for TI's packing materials are available at www.ti.com/eoinfo.

TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain limited information to be proprietary, and thus CAS numbers and other limited information may not be available for release. TI's standard warranty and limitation of liability provisions of TI's Standard Terms and Conditions (available at <http://www.ti.com/sc/docs/stdterms.htm>) apply to the representations herein unless otherwise provided by a written contract or other agreement signed by the parties.

Signature: [\(click here for signed certificate\)](#)

Name/Title: Cindy Allen, Vice President, Worldwide Quality

Date: September 27, 2006

Pb-Free: TI defines "Pb-Free" or "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials unless exempt. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes.

Green: TI defines "Green" to mean Pb-Free/RoHS Compliant and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material).